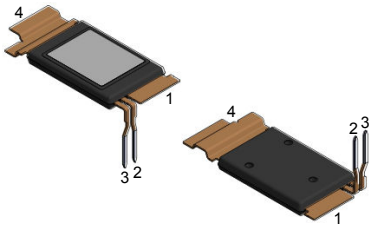
EXHIBIT 2

life.augmented

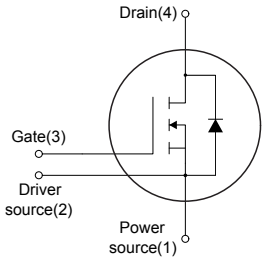
SCTHS250N65G2G

Datasheet

Automotive-grade silicon carbide Power MOSFET 650 V, 8.0 mΩ typ., 250 A in a STPAK package



STPAK



NG3DS2PS1D4

STPOWER

Product status link
SCTHS250N65G2G

Product summary	
Order code	SCTHS250N65G2G
Marking	SCHS250N65G2
Package	STPAK
Packing	Tray

Features

Order code	V_{DS}	$R_{DS(on)}$ typ.	I_D
SCTHS250N65G2G	650 V	8.0 mΩ	250 A

- AEC-Q101 qualified
- Very fast and robust intrinsic body diode
- Extremely low gate charge and input capacitance
- Source sensing pin for increased efficiency

Applications

- Main inverter (electric traction)
- DC/DC converter for EV/HEV

Description

This silicon carbide Power MOSFET device has been developed using ST's advanced and innovative 2nd generation SiC MOSFET technology. The device features remarkably low on-resistance per unit area and very good switching performance. The variation of switching loss is almost independent of junction temperature.

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	-10 to 22	V
	Gate-source voltage (recommended operating values)	-5 to 20	
I_D	Drain current (continuous) at T_C = 25 °C	250	A
	Drain current (continuous) at T_C = 100 °C	178	
I_D(1)	Drain current (pulsed)	750	A
P_{TOT}	Total power dissipation at T_C = 25 °C	790	W
V_{ISO}	Insulation withstand voltage (DC) from all three leads to external heat sink (t = 1 s; T_C = 25 °C)	4.3	kV
T_J	Operating junction temperature range	-55 to 175	°C
T_{stg}	Storage temperature range		°C

1. *Pulse width limited by safe operating area.*

Table 2. Thermal data

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Thermal resistance, junction-to-case	-	0.14	0.19	°C/W

2 Electrical characteristics

T_C = 25 °C unless otherwise specified.

Table 3. On-/off-states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	650			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 650 V			40	µA
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = 22 V			100	nA
		V_{DS} = 0 V, V_{GS} = 20 V			20	nA
		V_{DS} = 0 V, V_{GS} = -5 V	-20			nA
		V_{DS} = 0 V, V_{GS} = -10 V	-100			nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 2.5 mA	1.5	2.9	4.0	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 20 V, I_D = 95 A	5.8	8.0	10.9	mΩ

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{GS} = 0 V, V_{DS} = 400 V, f = 1 MHz	4900	7000	9100	pF
C_{oss}	Output capacitance		490	700	910	pF
C_{rss}	Reverse transfer capacitance		119	170	221	pF
R_g	Intrinsic gate resistance	f = 1 MHz, I_D = 0 A	0.3	0.8	1.3	Ω
Q_g	Total gate charge	V_{DD} = 400 V, I_D = 95 A, V_{GS} = 0 to 20 V		400		nC
Q_{gs}	Gate-source charge			80		nC
Q_{gd}	Gate-drain charge			170		nC

Table 5. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
E_{on}	Turn-on switching energy	V_{DD} = 400 V, I_D = 95 A,	-	1100	-	µJ
E_{off}	Turn-off switching energy	$R_{G(on)}$ = 12 Ω, $R_{G(off)}$ = 10 Ω, V_{GS} = -5 to 20 V, L_s = 100 nH	-	2500	-	µJ

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 400 V, I_D = 95 A, R_G = 10 Ω, V_{GS} = -5 to 20 V	-	140	-	ns
t_r	Rise time		-	350	-	ns
$t_{d(off)}$	Turn-off delay time		-	230	-	ns
t_f	Fall time		-	130	-	ns

Table 7. Reverse SiC diode characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode forward voltage	I_{SD} = 200 A, V_{GS} = -5 V	3.0	5.7	7.0	V
t_{rr}	Reverse recovery time	I_{SD} = 95 A, di/dt = 3100 A/µs, V_{DD} = 400 V		40		ns
Q_{rr}	Reverse recovery charge			1160		nC
I_{RRM}	Reverse recovery current			49		A

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

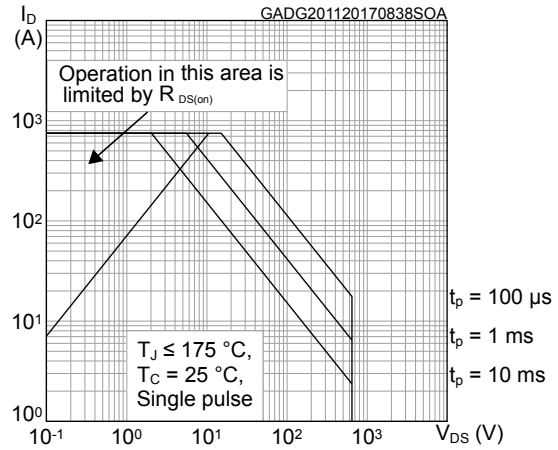


Figure 2. Normalized thermal impedance

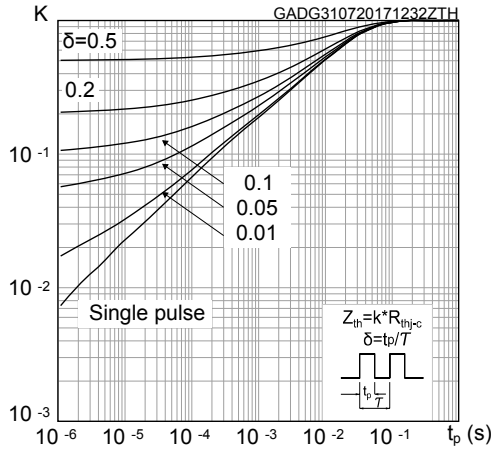


Figure 3. Output characteristics (T_J = 25 °C)

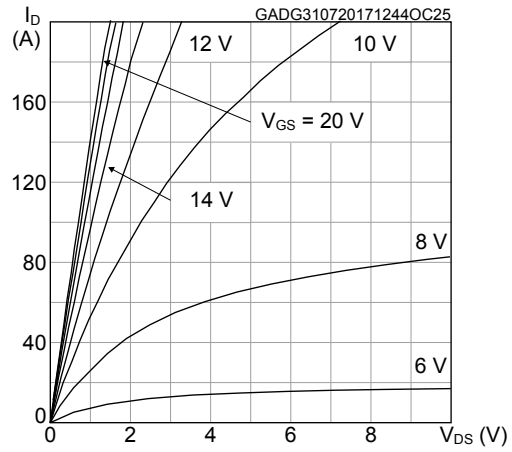


Figure 4. Output characteristics (T_J = 175 °C)

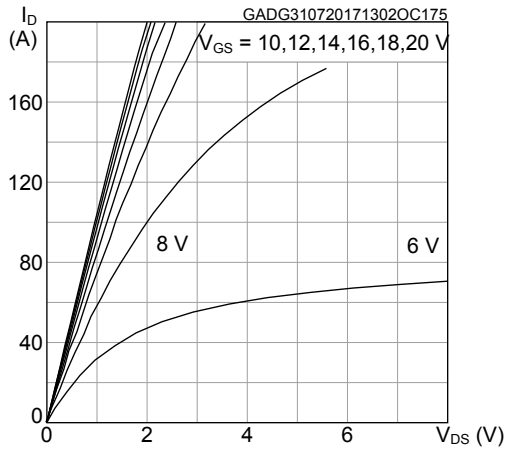


Figure 5. Transfer characteristics

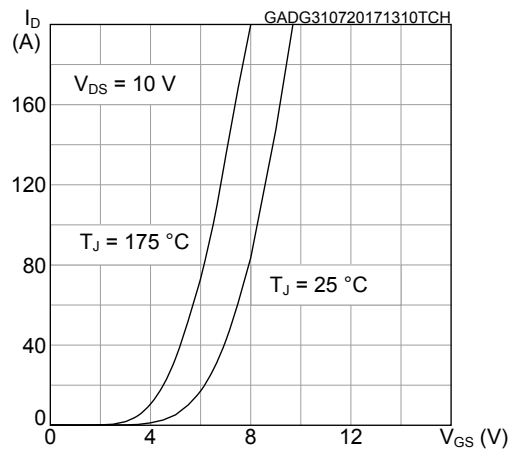


Figure 6. Power dissipation

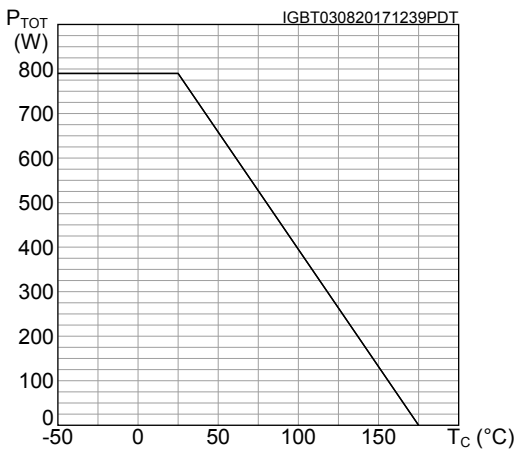


Figure 7. Gate charge vs gate-source voltage

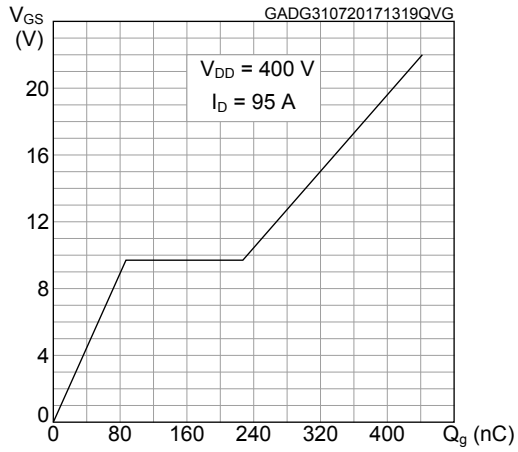


Figure 8. Capacitance variations

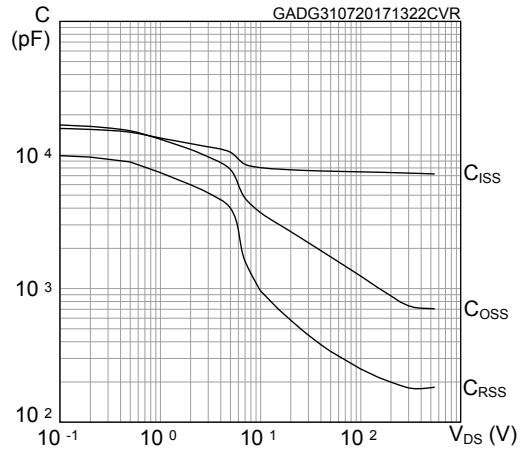


Figure 9. Switching energy vs drain current

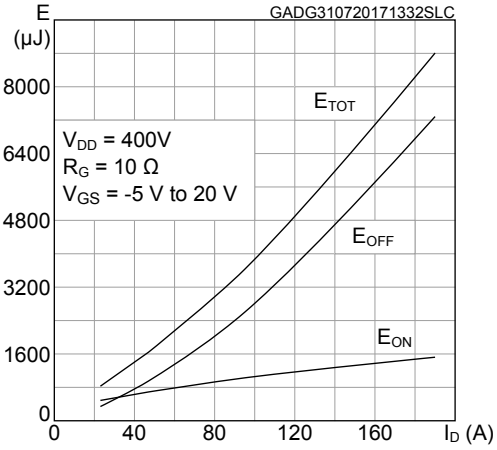


Figure 10. Switching energy vs junction temperature

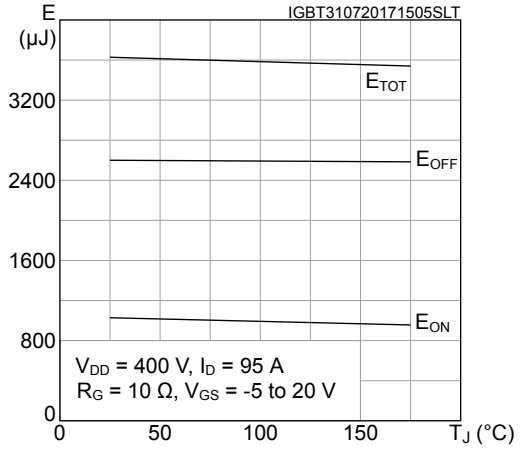


Figure 11. Switching energy vs R_g

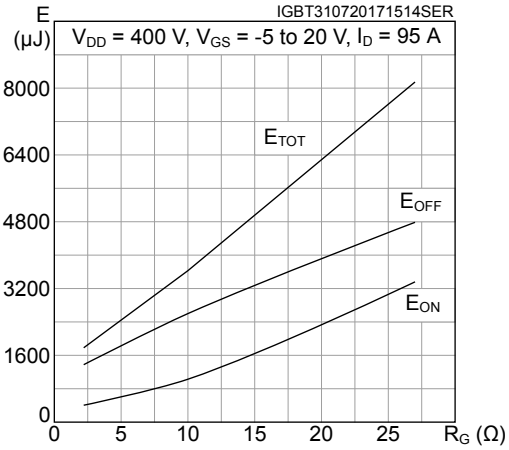


Figure 12. Normalized $V_{(BR)DSS}$ vs temperature

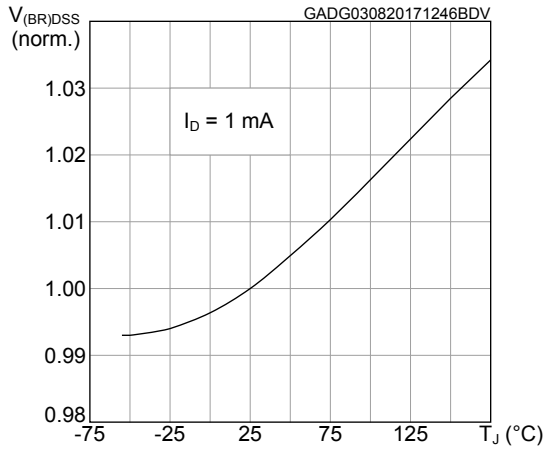


Figure 13. Normalized gate threshold voltage vs temperature

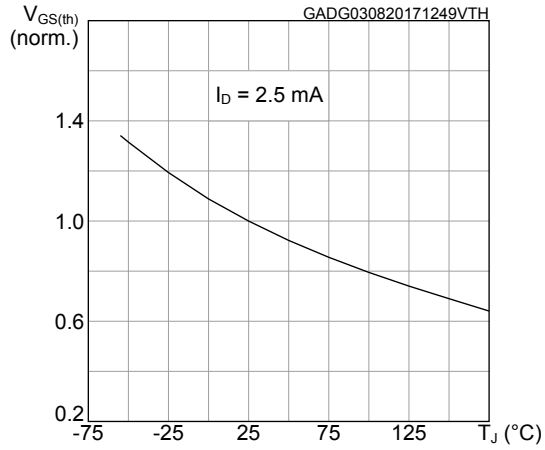


Figure 14. Normalized on-resistance vs temperature

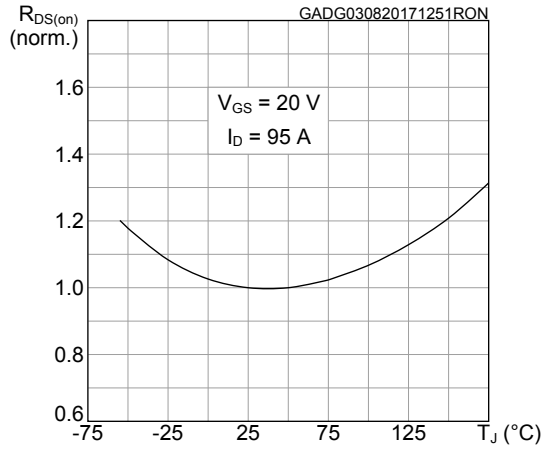


Figure 15. Body diode characteristics (T_J = 25 °C)

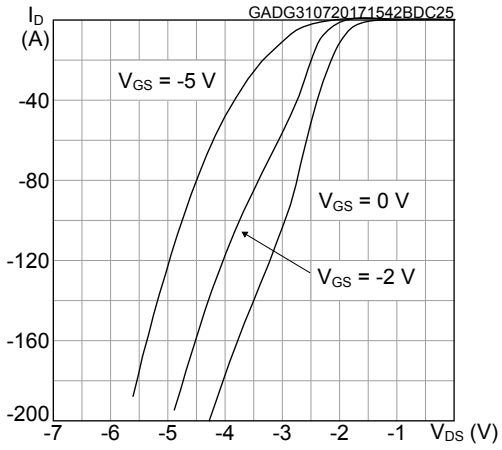


Figure 16. Body diode characteristics (T_J = 175 °C)

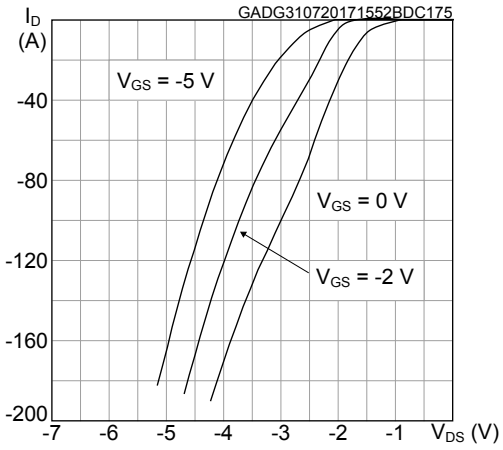


Figure 17. 3rd quadrant characteristics (T_J = 25 °C)

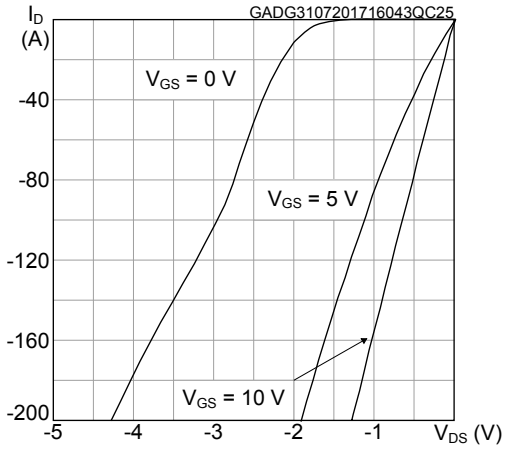
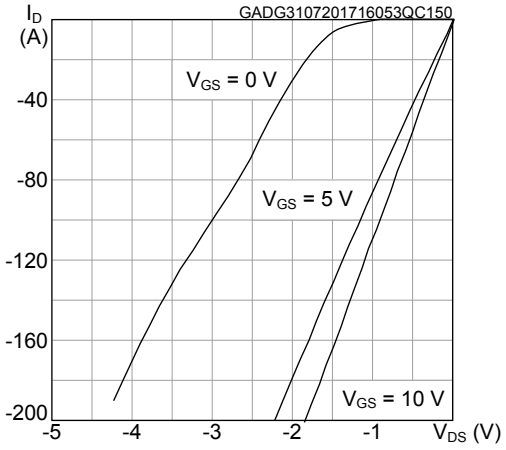


Figure 18. 3rd quadrant characteristics (T_J = 175 °C)

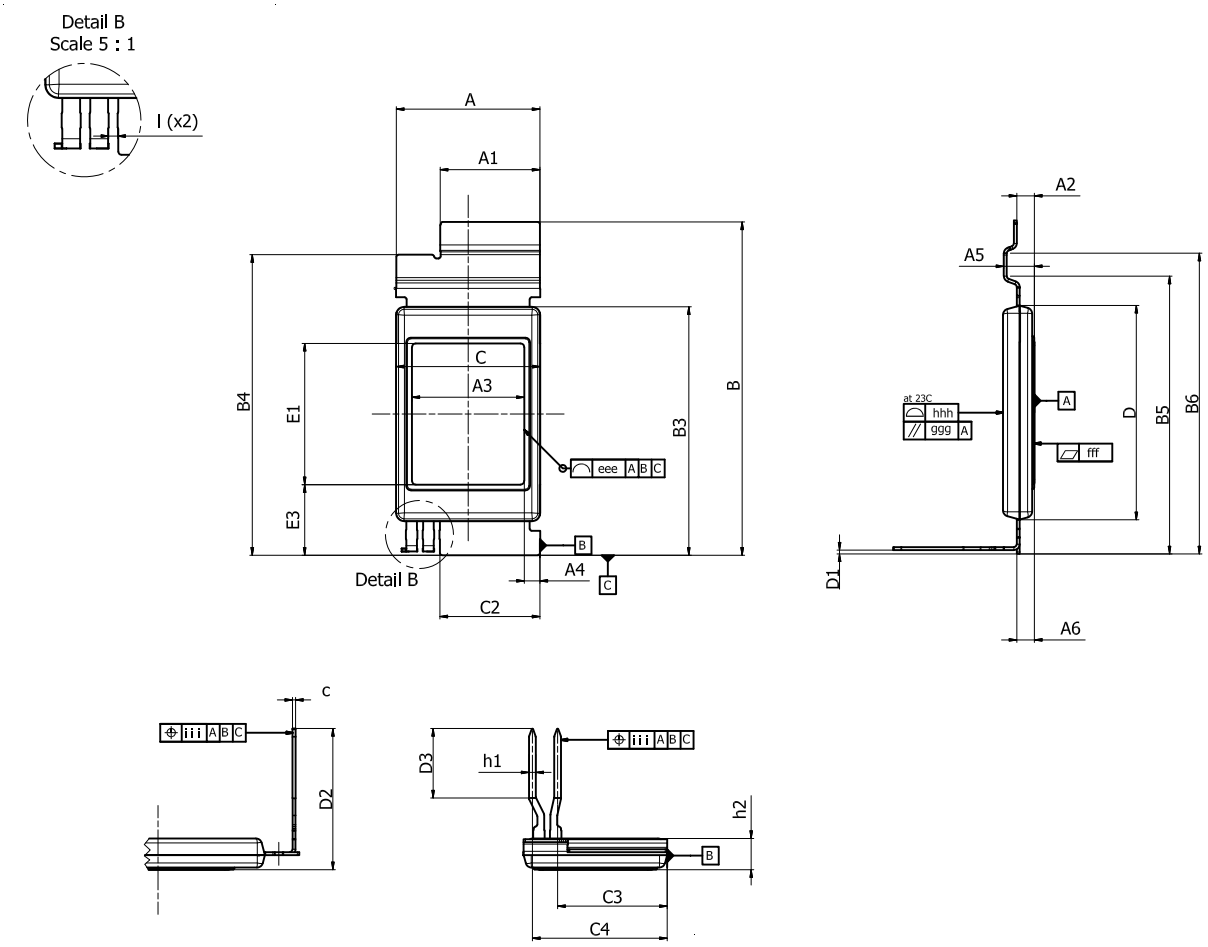


3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 STPAK package information

Figure 19. STPAK package outline



DM00305987_7

Table 8. **STPAK package mechanical data**

Ref.	Dimensions			Notes
	mm			
	Min.	Typ.	Max.	
A	18.60	18.80	19.00	
A1	12.85	13.05	13.25	
A2	2.00	2.30	2.60	
A3	14.20	14.70	15.20	Exposed Pad
A4	1.55	2.05	2.55	
A5	3.80	4.00	4.20	
A6	2.10	2.30	2.50	
B	43.40	43.70	44.00	
B3	32.20	32.50	32.80	
B4	39.10	39.40	39.70	
B5	36.07	36.37	36.67	
B6	39.07	39.37	39.67	
c	0.34	0.39	0.44	
C		18.55	19.10	Encompass both large and small cav.
C2	12.90	13.10	13.30	
C3		14.35		
C4		17.65		
D	27.90	28.10	28.30	
D1		0.69		
D2	18.00 (18.50)	18.50 (19.00)	19.00 (19.50)	Refer to the values in brackets for the longer pins type
D3	8.60 (9.10)	9.10 (9.60)	9.60 (10.10)	Refer to the values in brackets for the longer pins type
E1	18.00	18.50	19.00	Exposed pad
E3	8.75	9.25	9.75	
h1	0.85	0.90	0.95	x2 - Pins width
h2	4.00	4.10	4.20	
l	0.60	0.70	0.80	
eee	0.50			
fff	0.10 at 23 °C – 0.05 at 220 °C			Convex with center higher than edges
ggg	0.05			
hhh	0.10			
iii	0.60			

Revision history

Table 9. **Document revision history**

Date	Revision	Changes
27-Apr-2023	1	First release.

Contents

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